External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0.001	2.0	0.02
	Lead alloy	Silver (Ag)	7440-22-4	0.00124	2.5	0.025
	Lead alloy	Lead (Pb)	7439-92-1	0.04754	95.5	0.955
			Subtotal	0.04978	100	1
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.0066	100.0	0.13254
			Subtotal	0.0066	100	0.13254
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.03335	100.0	0.67
			Subtotal	0.03335	100	0.67
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.74671	100.0	15
			Subtotal	0.74671	100	15
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02116	0.03	0.4251
	Copper alloy	Iron (Fe)	7439-89-6	0.07054	0.1	1.417
	Copper alloy	Copper (Cu)	7440-50-8	70.30676	99.67	1,412.3239
	Copper alloy	Silver (Ag)	7440-22-4	0.14108	0.2	2.834
			Subtotal	70.53954	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.86056	6.5	37.375
	Polymer	Epichlorohydrin/o- Cresol/Formaldehyde polymer (generic)	29690-82-2	4.57984	16.0	92
	Filler	Silica fused	60676-86-0	20.32305	71.0	408.25
	Flame retardant	Metal hydroxide		1.86056	6.5	37.375
			Subtotal	28.62401	100	575
			Total	99.99999	100	NaN

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